

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3005	257/787	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 16:06
L2	1717	257/734	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 16:18
L3	2295	257/784	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 16:51
L4	2016	438/612	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 17:01
L5	1	257/E23.02	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 17:02
L6	0	257/E21.523	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 17:02
L7	0	257/E21.59	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 17:03
L8	0	257/E23.026	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/28 17:03

S1	12	"5838023".pn. or "6605854".pn. or "5726501".pn. or "6011301".pn. or "6452281".pn. or "6445001".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/22 13:09
S2	6	"5838023".pn. or "6605854".pn. or "5726501".pn. or "6011301".pn. or "6452281".pn. or "6445001".pn.	USPAT	OR	ON	2004/06/22 13:32
S3	16	"5045151".pn. or "5525546".pn. or "6211576".pn. or "6482730".pn. or "6525424".pn. or "6452284".pn. or "6677682".pn. or "6507092".pn. or "6392300".pn. or "5360988".pn. or "6445001".pn. or "6022791".pn. or "6677682".pn. or "6583506".pn. or "6746898".pn. or "6664640".pn. or "55056650".pn.	USPAT; JPO	OR	ON	2004/06/22 13:13
S4	24	"5726501"	USPAT	OR	ON	2004/06/22 13:32
S5	3159	257/676	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 13:26
S6	2225	257/676	USPAT	OR	ON	2004/06/21 19:07
S7	934	257/676 not 257/676	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 19:07
S8	1174	257/687	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 19:19
S9	2	"20020003293"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 19:14
S10	2611	257/690	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 19:40
S11	1824	257/690	USPAT	OR	ON	2004/06/21 19:20

S12	787	257/690 not 257/690	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 19:24
S13	3895	257/778	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 20:10
S14	3379	257/778 not 257/778	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 19:42
S15	516	257/778	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 19:46
S16	1647	257/779	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 20:13
S17	1924	257/780	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 20:34
S18	992	257/781	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 20:55
S19	1036	257/782	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 21:16
S20	1593	257/783	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 21:26
S21	2516	257/786	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 22:00

S22	522	257/786	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 21:27
S23	1994	257/786 not 257/786	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 21:41
S24	592	257/789	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 22:03
S25	462	257/798	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 22:07
S26	2655	257/738	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 22:18
S27	315	257/738	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 22:08
S28	2340	257/738 not 257/738	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 22:09
S29	1912	257/701	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/06/21 22:19
S30	7	"6858944" or "6452284"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/25 13:27
S31	10048	(semiconductor or die or chip or IC) same (pad or terminal or contact) with (depression or indentation or slot or groove)	USPAT; JPO	OR	ON	2005/03/25 22:00
S32	1908	(semiconductor or die or chip or IC) same (pad) with (depression or indentation or slot or groove)	USPAT; JPO	OR	ON	2005/03/25 17:17

S33	288	(semiconductor or die or chip or IC) same (pad or terminal or contact) with (depression or indentation or slot or groove or trench or hole) with (encapsulat\$3 or resin or mold\$3) with fill\$3	USPAT; JPO	OR	ON	2005/03/25 21:23
S34	4760	(semiconductor or die or chip or IC) and (pad or terminal or contact) with (depression or indentation or slot or groove or trench or hole) with (encapsulat\$3 or resin or mold\$3)	USPAT; JPO	OR	ON	2005/03/25 21:23
S35	2347	(semiconductor or die or chip or IC) same (pad or terminal or contact) with (depression or indentation or slot or groove or trench or hole) with (encapsulat\$3 or resin or mold\$3)	USPAT; JPO	OR	ON	2005/03/25 21:24
S36	2059	S35 not S33	USPAT; JPO	OR	ON	2005/03/25 21:24
S37	2278	(semiconductor or die or chip or IC) same (pad or terminal or contact) with (slot or groove or trench or hole) with (encapsulat\$3 or resin or mold\$3)	USPAT; JPO	OR	ON	2005/03/25 21:25
S38	2059	S36 not S33	USPAT; JPO	OR	ON	2005/03/25 21:25
S39	749	(semiconductor or die or chip or IC) same (pad) with (slot or groove or trench or hole) with (encapsulat\$3 or resin or mold\$3)	USPAT; JPO	OR	ON	2005/03/25 21:25
S40	610	S39 not S33	USPAT; JPO	OR	ON	2005/03/25 21:25
S41	238	(semiconductor or die or chip or IC) same (pad or terminal or contact) with (depression or indentation or slot or groove) with adhes\$3	USPAT; JPO	OR	ON	2005/03/25 22:08
S42	888	(semiconductor or die or chip or IC) same (pad or terminal or contact) with (depression or indentation or slot or groove) with area	USPAT; JPO	OR	ON	2005/03/25 22:08
S43	54	(semiconductor or die or chip or IC) same (pad or terminal or contact) with (depression or indentation or slot or groove) with area with (resin or encapsulat\$3 or mold\$3)	USPAT; JPO	OR	ON	2005/03/25 22:09